

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TAEGYU JIN	07/04/2019
YONG KI JEONG	07/04/2019
JANGHEE PARK	07/04/2019
RECEIVING PARTY DATA	
Name:	LG ELECTRONICS INC.
Street Address:	128, YEQUI-DAERO, YEONGDEUNGPO-GU
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State/Country:	KOREA, REPUBLIC OF
Postal Code:	07336
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16479479
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NAME OF SUBMITTER:	YONG S. CHOI
SIGNATURE:	/Yong S. Choi/
DATE SIGNED:	07/19/2019
Total Attachments: 2	
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source=ASSIGNMENT#page2.tif	

Assignment of Application

WHEREAS, I (WE)	Taegy JIN, Yong Ki JEONG, and Janghee PARK
	, respectively,
have invented certain new and useful improvements in:	
ORGANIC POLIMER ABSORBENT, COMPOSITION OF ORGANIC POLIMER ABSORBENT AND METHOD OF MANUFACTURING THEREOF	
for which an application for Letters Patent was executed on	

(Application No.		, Filed), and
WHEREAS,	LG ELECTRONICS INC.			
(hereinafter referred to as "ASSIGNEE") having a place of business at: 128, Yeoui-daero, Yeongdeungpo-gu, Seoul 07336, Republic of Korea				

is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;

NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt whereof is hereby acknowledged, and for other good and valuable consideration, I (WE), by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.

I (WE) hereby authorize and request the Patent Office Officials in the United States and Its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my (our) entire right, title and interest in and to the same, for the sole use and behalf of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me (us) had this Assignment and sale not been made.

Further, I (WE) agree that I (WE) will communicate to said ASSIGNEE or its (his) representatives any facts known to me (us) respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

The undersigned hereby grant(s) the firm of DENTONS US LLP, Attorneys at Law, 1900 K Street, N.W., Washington, D.C. 20006 the power to insert on this assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: July 4, 2019

진태규
(Signature of Inventor)
Taegyu JIN

Date: July 4, 2019

Yong Ki Jeong
(Signature of Inventor)
Yong Ki JEONG

Date: July 4, 2019

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